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**Standardizacija mehanskih lastnosti polprevodniških elementov - 6-20. del:  
Splošna pravila za izdelavo tehničnih risb površinsko montiranih sklopov  
polprevodniških elementov - Merilne metode za mere majhnih okrovov s priključki  
v obliki črke J (SOJ) (IEC 60191-6-20:2010)**

Mechanical standardization of semiconductor devices - Part 6-20: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Measuring methods for package dimensions of small outline J-lead packages (SOJ) (IEC 60191-6-20:2010)

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Mechanische Normung von Halbleiterbauelementen - Teil 6-20: Allgemeine Regeln für die Erstellung von Gehäusezeichnungen von SMD-Halbleitergehäusen - Messverfahren für Gehäusemaße von kleinen Gehäusen mit J-förmigen Anschlüssen (SOJ) (IEC 60191-6-20:2010)

Normalisation mécanique des dispositifs à semiconducteurs - Part 6-20: Règles générales pour la préparation des dessins d'encombrement des boîtiers pour dispositifs à semiconducteurs pour montage en surface - Méthodes de mesure pour les dimensions des boîtiers à sortie en J (SOJ) de faible encombrement (CEI 60191-6-20:2010)

**Ta slovenski standard je istoveten z: EN 60191-6-20:2010**

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**ICS:**

01.100.25	Risbe s področja elektrotehnike in elektronike	Electrical and electronics engineering drawings
31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general

**SIST EN 60191-6-20:2010**

**en**

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EUROPEAN STANDARD  
NORME EUROPÉENNE  
EUROPÄISCHE NORM

**EN 60191-6-20**

October 2010

ICS 31.080.01

English version

**Mechanical standardization of semiconductor devices -  
Part 6-20: General rules for the preparation of outline drawings of surface  
mounted semiconductor device packages -  
Measuring methods for package dimensions of small outline J-lead  
packages (SOJ)  
(IEC 60191-6-20:2010)**

Normalisation mécanique des dispositifs à  
semiconducteurs -  
Part 6-20: Règles générales pour la  
préparation des dessins d'encombrement  
des boîtiers pour dispositifs à  
semiconducteurs pour montage en  
surface -  
Méthodes de mesure pour les dimensions  
des boîtiers à sortie en J (SOJ) de faible  
encombrement  
(CEI 60191-6-20:2010)

Mechanische Normung von  
Halbleiterbauelementen -  
Teil 6-20: Allgemeine Regeln für die  
Erstellung von Gehäusezeichnungen von  
SMD-Halbleitergehäusen -  
Messverfahren für Gehäusemaße von  
kleinen Gehäusen mit J-förmigen  
Anschlüssen (SOJ)  
(IEC 60191-6-20:2010)

INTERNATIONAL STANDARD PREVIEW  
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**CENELEC**

European Committee for Electrotechnical Standardization  
Comité Européen de Normalisation Electrotechnique  
Europäisches Komitee für Elektrotechnische Normung

**Management Centre: Avenue Marnix 17, B - 1000 Brussels**

## Foreword

The text of document 47D/771/FDIS, future edition 1 of IEC 60191-6-20, prepared by SC 47D, Mechanical standardization for semiconductor devices, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60191-6-20 on 2010-10-01.

Attention is drawn to the possibility that some of the elements of this document may be the subject of patent rights. CEN and CENELEC shall not be held responsible for identifying any or all such patent rights.

The following dates were fixed:

- latest date by which the EN has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2011-07-01
- latest date by which the national standards conflicting with the EN have to be withdrawn (dow) 2013-10-01

Annex ZA has been added by CENELEC.

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### Endorsement notice

The text of the International Standard IEC 60191-6-20:2010 was approved by CENELEC as a European Standard without any modification. (standards.iteh.ai)

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## Annex ZA (normative)

### Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60191-4	-	Mechanical standardization of semiconductor devices - Part 4: Coding system and classification into forms of package outlines for semiconductor device packages	EN 60191-4	-
IEC 60191-6	-	Mechanical standardization of semiconductor devices - Part 6: General rules for the preparation of outline drawings of surface mounted semiconductor device packages	EN 60191-6	-

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IEC 60191-6-20

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# INTERNATIONAL STANDARD

## NORME INTERNATIONALE

**Mechanical standardization of semiconductor devices –  
Part 6-20: General rules for the preparation of outline drawings of surface  
mounted semiconductor device packages – Measuring methods for package  
dimensions of small outline J-lead packages (SOJ)**

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Méthodes de mesure pour les dimensions des boîtiers à sortie en J (SOJ) de  
faible encombrement**

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –****Part 6-20: General rules for the preparation of outline drawings  
of surface mounted semiconductor device packages –  
Measuring methods for package dimensions  
of small outline J-lead packages (SOJ)**

## FOREWORD

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International Standard IEC 60191-6-20 has been prepared by subcommittee 47D: Mechanical standardization of semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47D/771/FDIS	47D/775/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directive, Part 2.



A list of all the parts in the IEC 60191 series, under the general title *Mechanical standardization of semiconductor devices*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

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